

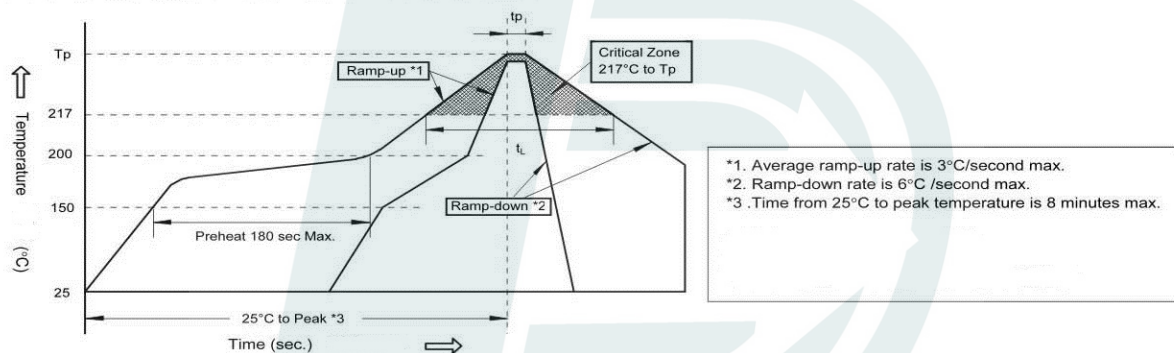
V-CHIP ALUMINUM ELECTROLYTIC CAPACITORS
REFLOW SOLDERING CONDITIONS

Applicable to Chip Type Aluminum Electrolytic Capacitors

■ Recommended Conditions for Reflow Soldering

- (1) A thermal condition system such as infrared radiation (IR) or hot blast shall be adopted, and vapor heat transfer systems(VPS) are not recommended.
- (2) Reflow soldering shall be done within 2 cycles. Please make sure that the parts have enough cooling time.
- (3) ■ The time of preheating from 150°C to 200°C shall be within 180 seconds;
 - The time of soldering temperature at 217°C measured on capacitors' top shall not exceed t_L (second);
 - The peak temperature on capacitors' top shall not exceed T_p (°C), and the time within 5°C of actual peak temperature shall not exceed t_p (second).

■ Classification Reflow Profile

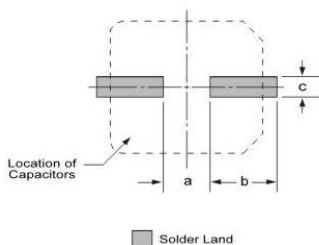


■ Classified at Temperature and Time Only for Standard Size without ()

Size 尺寸	Thickness(mm)	Volume(mm ³)	T_p (°C)	t_L (second)	T_p (second)
$\phi 4 \sim \phi 6.3, \phi 8 \times 6.2L$	≥ 2.5	< 350	250 ± 0	60	5
$\phi 8 \times 10.5L$	≥ 2.5	$350 \sim 2000$	240 ± 0	60	5
$\phi 10 \times 10.5L/13.5L$	≥ 2.5	$350 \sim 2000$	235 ± 0	60	5
$\phi 12.5, \phi 16$	≥ 2.5	> 2000	230 ± 0	30(20*)	5

Re: (20*) is special for mid-to-high voltage which is HU series.

■ Recommended Solder Land Size no PC Board(Unit: mm)



Size 尺寸	a	b	c
$\phi 4$	1.0	2.6	1.6
$\phi 5$	1.4	3.0	1.6
$\phi 6.3$	2.1	3.5	1.6
$\phi 8 \times 6.2L$	2.1	4.5	1.6
$\phi 8 \times 10.5L$	3.0	3.5	2.5
$\phi 10$	4.0	4.0	2.5
$\phi 12.5$	4.0	5.7	3.0
$\phi 16$	6.0	6.5	3.5

NOTE: All designs and specifications are for reference only and are subject to change without prior notice. If any doubt about safety for your application, please contact us immediately for technical assistance before purchase.